

ABSTRACT OF THE DISCLOSURE

**HIGH DENSITY ELECTRICAL INTERCONNECT SYSTEM**  
**HAVING ENHANCED GROUNDING AND**  
**CROSS-TALK REDUCTION CAPABILITY**

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Disclosed is an electrical interconnect system using multiple grounding methods to reduce or prevent spurious signals from interfering with high density contacts carrying high speed transmissions. A first connector includes an insulative pillar partially surrounded by a plurality of signal contacts. A ground contact is at least partially located within the insulative pillar. A second connector includes a corresponding plurality of flexible signal contacts for mating with the signal contacts adjacent the insulative pillar. The second connector also includes a ground contact for receiving the ground contact of the first connector.

10 The ground contacts provide a first method of providing a ground path to reduce spurious signals from entering the signal path. An electrically conducting shield is located outside the signal contacts when the first and the second connectors are mated. The first connector includes a member which provides a ground path between the first connector and the electrically conducting shield.

15 Advantageously, the electrical interconnect system has two grounding methods which are particularly important in a high density electrical interconnect system where the contacts are closely spaced and susceptible to noise and other spurious signals.

25 [Figure 14]



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